3D Computer Vision and 3D Reconstruction

Guest Editors:

Dr. Yilong Li
School of Instrumentation and Optoelectronic Engineering, Beihang University, Beijing 100191, China

Dr. Di Wang
School of Instrumentation and Optoelectronic Engineering, Beihang University, Beijing 100191, China

Prof. Dr. Huan Deng
College of Electronics and Information Engineering, Sichuan University, Chengdu 610065, China

Deadline for manuscript submissions:
31 March 2025

Message from the Guest Editors

The Special Issue aims to explore the latest advancements and innovations in the field of 3D computer vision and 3D reconstruction techniques. The topics include, but are not limited to:

(1) 3D information acquisition and processing;

(2) 3D reconstruction methods;

(3) computer vision;

(4) deep learning for 3D systems;

(5) emerging optical materials for 3D reconstruction.

Special Issue

Editor-in-Chief

Prof. Dr. Flavio Canavero
Department of Electronics and Telecommunications, Politecnico di Torino, 10129 Torino, Italy

Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guest-edited by leading experts in selected topics of interest.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.
High Visibility: indexed within Scopus, SCIE (Web of Science), CAPlus / SciFinder, Inspec, Ei Compendex and other databases.
Journal Rank: JCR - Q2 (*Physics, Applied*) / CiteScore - Q2 (*Control and Systems Engineering*)

Contact Us